

TECHNICAL DATA

SOLBOND H180 ROUND - Self-Bonding Enamelled Copper Wire

DESCRIPTION

Solbond H180 wires are designed to bond together turn to turn without the need of impregnating varnishes and resins.

As well as having a bond coat, Solbond H180 wires are directly solderable without having to remove the enamel.

Solbond H180 wires are easily bonded with heat in the production process, resulting in coils of high bond strength, as well as increasing productivity of the production line.

APPLICATIONS

Stators and rotors of micro-motors, TV/monitor deflection yokes, solenoid coils, loud-speaker coils.

PROPERTIES

Temperature class	180°C
Enamel - Base coat	Polyurethane
Enamel - Bond coat	Modified Butyral or Aliphatic Polyamide
Diameters	0.150 - 2.000mm
Grades	G-1B, G-2B
Colours	Natural
Bonding temperature	140/170°C
Re-softening temperature	120/155°C
Breakdown voltage	1.5 x IEC value
Heat shock	> 175°C
Solderability	470°C for 4 seconds
Cut through	≥ 250°C
Chemical resistance	Good
Methods of test	IEC 60851
Standards (Enamel)	N/A
Standards (Packaging)	IEC 60264